



5/9/2009

RELIABILITY MONITOR REPORT
FOR

Flip Chip Package

MAXIM Integrated Products

120 San Gabriel Dr.
Sunnyvale, CA 94086

This Report was prepared by
Maxim Reliability Engineering

Summary:

The data in the tables that follow was generated as the result of an on-going Package Reliability Monitor. The specific assemblies included in this package monitor are:

ASSY SITE	PINS PACKAGE
Dallas-8	2 Flip Chip RDL (Solder Bump)

Note: Due to the nature of the construction on this assembly, there is no operating life data collected.

The reliability data follows. At the start of this data is a description of the assembly vehicle used to generate this reliability data. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available. This report covers data between 1/1/2008 and 12/31/2008.

Assembly Information:

Package Type: Flip Chip RDL (Solder Bump)
 Flammability: UL 94-V0
 Date Code Range: 0749 to 0803

TEMPERATURE CYCLE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
TEMP CYCLE, 5' RAMP, 10' DWELL	0749	DS2502	-40 TO 85C	1000 CYS	80	0	
TEMP CYCLE, 5' RAMP, 10' DWELL	0749	DS2502	-40 TO 85C	1000 CYS	80	0	
TEMP CYCLE, 5' RAMP, 10' DWELL	0749	DS2502	-40 TO 85C	1000 CYS	80	0	
TEMP CYCLE, 5' RAMP, 10' DWELL	0749	DS2502	-40 TO 85C	1000 CYS	80	0	
TEMP CYCLE, 5' RAMP, 10' DWELL	0802	DS2502	-40C TO +125C	1000 CYS	231	0	
TEMP CYCLE, 5' RAMP, 10' DWELL	0802	DS2502	-40C TO +125C	1000 CYS	231	0	
TEMP CYCLE, 5' RAMP, 10' DWELL	0802	DS2502	-40C TO +125C	1000 CYS	231	0	
TEMP CYCLE, 5' RAMP, 10' DWELL	0803	DS2502	-40C TO +125C	1000 CYS	231	0	
Total:						0	

UNBIASED MOISTURE RESISTANCE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
HAST, NO BIAS	0802	DS2502	130C, 85% R.H.	96 HRS	231	0	
HAST, NO BIAS	0802	DS2502	130C, 85% R.H.	96 HRS	231	0	
HAST, NO BIAS	0802	DS2502	130C, 85% R.H.	96 HRS	231	0	
HAST, NO BIAS	0803	DS2502	130C, 85% R.H.	96 HRS	231	0	
Total:						0	